

11/24/97  
JCS56 U.S. PTO

Docket No. Halo-010

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE  
Certification under 37 CFR §1.10 (if applicable)

EM 427 196 973 US  
"Express Mail" Label Number

11/24, 1997  
Date of Deposit

I hereby certify that this Transmittal letter, enclosed application, and any other documents referred to as enclosed herein are being deposited in an envelope with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR §1.10 on the date indicated above and addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231

Stephen E. Baldwin, Reg. No. 27,769  
(Name of Person Mailing Application)

*Stephen E. Baldwin*  
(Signature of Person Mailing Application)

Transmittal of Utility Patent Application  
for Filing Under 37 CFR §1.53

Box Patent Application  
Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

Transmitted herewith for filing is a continuation-in-part utility patent application by inventor(s): Peter Lu, Jeffrey Heaton, James W. Heaton, Tsang Kei Sun, Peter Loh Hang Pao, and Robert Loke Hang Lam entitled:

ELECTRONIC SURFACE MOUNT PACKAGE WITH EXTENDED SIDE RETAINING WALL

Enclosed are:

- x A duplicate copy of this Transmittal Letter.
  - x One stamped, self-addressed postcard for the PTO Mail Room date stamp.
  - x One utility patent application containing pages 1-18, and
    - x a Declaration for Patent Application,
    - x 1 copy of 11 sheets of informal drawings.
- Power of Attorney by Assignee and Exclusion of Inventor(s) under Rule 32.  
Verified Statement Claiming Small Entity Status.  
An Assignment with its Transmittal Sheet.

Please charge Deposit Account No. \_\_\_\_\_ in the amount of \$ \_\_\_\_\_.

2. The filing fee has been calculated as shown below:

For:	(Col. 1)	(Col. 2)	Small Entity			Other Than a Small Entity	
	No. Filed	No. Extra	Rate	Fee		Rate	Fee
Basic Fee				\$ 395.00	or		\$ 790.00
Total Claims	8 - 20	0	x \$ 11 =	\$	or x \$ 22 =	\$	
Independent Claims	5 - 3	2	x \$ 41 =	\$ 82.00	or x \$ 82 =	\$	
9 Multiple Dependent Claim Presented			+ \$135 =	\$	or + \$270 =	\$	
* If the difference in Col. 1 is less than zero, enter "0" in Col. 2.			TOTAL	\$ 477.00	or TOTAL	\$	

A check in the amount of \$\_\_\_\_\_ is enclosed to cover the Filing Fee (\$\_\_\_\_\_.00)

The Commissioner is hereby authorized to charge fees under 37 CFR §1.16 and §1.17 which may be required, or credit any overpayment, to Deposit Account No.

3. The enclosed application is a continuation-in-part of copending continuation-in-part application entitled ELECTRONIC SURFACE MOUNT PACKAGE, Serial No. 08/773,555 filed December 27, 1996, which is a continuation-in-part application of Serial No. 08/513,573, filed August 10, 1995, now U.S. Patent No. 5,656,985, and assigned to the same Assignee as the present application.

Respectfully submitted,



Stephen E. Baldwin  
Registration No. 27,769

Date: Nov. 24, 1997

08977400-13497  
/64211 0047680

Correspondence Address:  
Trial & Technology Law Group  
Suite 220, 545 Middlefield Road  
Menlo Park, California 94025  
Telephone: (650) 324-2258

## DECLARATION FOR PATENT APPLICATION

As a below-named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name,

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled ELECTRONIC SURFACE MOUNT PACKAGE WITH EXTENDED SIDE RETAINING WALL, the specification of which:

(check one) ☒ is attached hereto  
was filed on  
Application Serial No.  
and was amended on

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose all information known to me to be material to patentability of this application as defined in Title 37, Code of Federal Regulations, §1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed: (none)

Prior Foreign Application(s)			<u>Priority Claimed</u>	
			<input type="checkbox"/>	<input type="checkbox"/>
(Number)	(Country)	(Day/Month/Year Filed)	Yes	No
			<input type="checkbox"/>	<input type="checkbox"/>
(Number)	(Country)	(Day/Month/Year Filed)	Yes	No

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, §1.56, which became available between the filing date of the prior application and the national or PCT international filing date of this application:

08/773,555      December 27, 1996      Pending  
(Application Serial No.)      (Filing Date)      (Status)(patented, pending, abandoned)

08/513,573      August 10, 1995      Now U.S. Patent No. 5,656,985  
(Application Serial No.)      (Filing Date)      (Status)(patented, pending, abandoned)

Direct all telephone calls to Stephen E. Baldwin at (650) 324-2258.

Address all correspondence to:

TRIAL & TECHNOLOGY LAW GROUP  
A Professional Law Corporation  
545 Middlefield Road, Suite 220  
Menlo Park, CA 94025

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18, United States Code, §1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor: Peter Lu

Inventor's signature: \_\_\_\_\_

Date: \_\_\_\_\_

Residence: 1708 Ingleside Drive, Flower Mound, TX 75028

Citizenship: U. S. Citizen

Post Office Address: 194 Civic Circle Lewisville, TX 75067

Full name of second joint inventor, if any: Jeffrey Heaton

Inventor's signature: \_\_\_\_\_

Date: \_\_\_\_\_

Residence: 7583 Normandy Way Cupertino, CA 95014

Citizenship: U. S. Citizen

Post Office Address: same

Full name of third joint inventor, if any: James W. Heaton

Inventor's signature: \_\_\_\_\_

Date: \_\_\_\_\_

Residence: 1963 Fallen Leaf Lane, Los Altos, CA 94024

Citizenship: U.S. Citizen

Post Office Address: same

Full name of fourth joint inventor, if any: Peter Loh Hang Pao

Inventor's signature: \_\_\_\_\_

Date: \_\_\_\_\_

Residence: 10 Carnarvon Road, 8/F, A-1, Kowloon, Hong Kong

Citizenship: China

Post Office Address: same

Full name of fifth joint inventor, if any: Robert Loke Hang Lam

Inventor's signature: \_\_\_\_\_

Date: \_\_\_\_\_

Residence: Flat A, 6/F, Block 3, Wonderland Villas, N.T.,  
Kowloon, Hong Kong

Citizenship: Hong Kong

Post Office Address: same

Full name of sixth joint inventor, if any: Tsang Kei Sun

Inventor's signature: \_\_\_\_\_

Date: \_\_\_\_\_

Residence: Flat F, 19/F, Tower One, Belvedere Garden, Phase Two,  
Tsuen Wan, Kowloon, Hong Kong

Citizenship: Hong Kong

Post Office Address: same

ELECTRONIC SURFACE MOUNT PACKAGE  
WITH EXTENDED SIDE RETAINING WALL

By: Peter Lu  
Jeffrey Heaton  
James W. Heaton  
Tsang Kei Sun  
Peter Loh Hang Pao  
Robert Loke Hang Lam

CROSS REFERENCE TO RELATED APPLICATIONS

The present application is a continuation-in-part of copending continuation-in-part application entitled ELECTRONIC SURFACE MOUNT PACKAGE, Serial No. 08/773,555 filed December 27, 1996, which is a continuation-in-part application of Serial No. 08/513,573, filed August 10, 1995, now U.S. Patent No. 5,656,985, and assigned to the same Assignee as the present application.

BACKGROUND OF THE INVENTION

The present invention relates to an electronic surface mount package or case and more particularly to an electronic surface mount package with an extended side retaining wall.

Electronic surface mount packages are utilized in applications in which one or more individual toroid transformers are embodied within the surface mount package.

Wires coming off the transformers are electronically tied to pins or posts on the package for connection to an electronic device. Typically, the electronic surface mount packages are mounted on a printed circuit board for utilization in the electronic device.

It is widely known in the local area magnetic industry that when surface mount toroidal magnetics which are encapsulated in hard plastics go through infra-red soldering processes, the

magnetic components (ferrite) can expand significantly. When using a hard epoxy type material, it has been found that the magnetic component expansion can often cause cracking of the package or case, which makes the part unusable. The electronic surface package described in the cross-referenced U.S. Patent No. 5,656,985 provides a soft silicone type material to encapsulate (carry) a plurality of toroid transformers within the package. The toroid transformers in turn are electrically connected to a plurality of terminal posts molded within the package. In view of the foregoing, it would be highly desirable to provide an improved electronic surface mount package which avoids the cracking and expansion problems described above and in addition provides additional coverage for the terminal pins to which the toroids are electrically connected as well as additional coverage for the soft silicone type material which encapsulates the toroids within the package.

#### SUMMARY OF THE INVENTION

It is an object of the present invention to provide an improved electronic surface mount package.

According to one preferred embodiment, the present invention provides a one piece construction package (with an open bottom) with one or more terminal pins molded into the package. Each of the pins have a notched post upon which a wire is wound and soldered. The wire which is wound and soldered around each terminal pin/post is from a respective toroid transformer carried within the package. Each of the posts are notched so that the respective wires are separated from one another so as to avoid arcing. The case is open at the bottom which prevents cracking and allows for the toroidal expansion. A soft silicone type material is added to the open package to provide support (to carry) the toroid transformers. In one embodiment, the present invention also includes a reinforcement beam that is disposed laterally or sidewise across the bottom of the package to provide extra support in the mechanical strength of the case. In another embodiment, the present invention also includes an extended side retaining wall for

retaining the soft silicone type material and providing additional coverage of the soft silicone material. the end walls have a first height H1 to form a standoff or safe guard between the foot seating plane of the package and the terminal pins; and the outer portion of the side wall extends between the end walls such that the side wall has a second height H2 which is less than said first height H1. The mounting of the package onto a printed circuit board (PCB) with the extended side retaining wall according to the present invention allows for cleaning of the PCB with wash liquids which can flow freely under the package under the portion of the extended side wall, since the height of the extended side retaining wall (H2) is less than the height of the safeguard H1 ( $H2 < H1$ ). The extended side retaining wall provides for improved containment of the soft silicone material within the package. The extended side retaining wall also provides for improved coverage of the wire wrapped solder posts.

Other objects, features, and advantages of the present invention will become apparent from the following detailed description when taken in conjunction with the accompanying drawings.

#### BRIEF DESCRIPTION OF THE DRAWINGS

The accompanying drawings, which are incorporated in and form a part of this specification, illustrate embodiments of the invention and, together with the description, serve to explain the principles of the invention:

Figure 1 shows an electronic surface mount package in three-dimensional view according to the present invention.

Figure 2 shows a wound toroid transformer.

Figure 3 shows the connection of the toroid transformer of Figure 2 within the electronic surface mount package of Figure 1.

Figure 4 shows the electronic surface mount package of Figure 1 after wire terminations



have been soldered.

Figure 5 and 6 show relationships between a safeguard (standoff) and the electronic surface-mount package's foot seating plane and inner terminal posts, respectively.

Figure 7 shows a close-up of the pin configuration of Figure 1 and how it is molded  
5 inside the wall of the body of the package.

Figure 8 shows wire wrapped around the pin or post of Figure 7.

Figures 9A -9D show end, top, side, and bottom views of electronic surface mount package according to the present invention.

Figure 10 shows a bottom view of a 40 pin package according to the present invention.

Figure 11 shows an enlarged sectional view of Figure 10 illustrating a reinforcement  
10 beam.

Figure 12 shows a three dimensional view of an electronic surface mount package with extended side retaining wall according to the present invention.

Figure 13 shows a bottom view of the electronic surface mount package with extended  
15 side retaining wall according to the present invention.

Figure 14 shows a more detailed view of the electronic surface mount package with extended side retaining wall according to the present invention.

Figure 15 shows a cross sectional end view of the electronic surface mount package with extended side retaining wall according to the present invention.

Figure 16 shows a close up view of one terminal pin contained within the electronic surface mount package with extended side retaining wall according to the present invention.  
20

#### DETAILED DESCRIPTION OF THE DRAWINGS

Reference will now be made in detail to the preferred embodiments of the invention,  
25 examples of which are illustrated in the accompanying drawings, where like numerals indicate like components. While the invention will be described in conjunction with the preferred

embodiments, it will be understood that they are not intended to limit the invention to those embodiments. On the contrary, the invention is intended to cover alternatives, modifications and equivalents, which may be included within the spirit and scope of the invention as defined by the appended claims.

5 As will be described in more detail below, the present invention is directed toward applications for packages mounted on a printed circuit board in an electronic device, which requires very low current and voltages, and is for DC voltages only. The present invention provides for a low power application in which the package includes one or more toroidal transformers which are carried or supported by a soft silicone material within an open  
10 construction package and which utilizes a portion of the case as a standoff to ensure that the pin-posts do not touch a PCB when mounted by a user.

As described above, it is known that when the parts go through an infra-red soldering process, the magnetic components (ferrite toroids) can expand significantly. When using a hard epoxy type material, it has been found that the magnetic component expansion can often cause  
15 cracking of the package or case, which is highly undesirable. The present invention solves this problem by providing an open design within which is placed a soft silicone material which allows for expansion during the soldering process, rather than trying to contain the components within a closed case or package. Hence, with the open construction, the present invention has no bottom at all. In addition, the magnetic components are not mounted on anything but rather are  
20 encapsulated or supported ("carried by a soft silicone material"). The wires from the toroids are wound around and soldered to the pin-posts. This construction solves the cracking and expansion problems described above, as will now be described in conjunction with Figures 1-17.

Figure 1 shows an electronic surface mount transformer package or case 10 in three-dimensional view. Figure 1 shows a cut-away of the empty case 10 with pins 14 molded into the  
25 case 10, together a the notched post 12 upon which a wire is wound. Post 12 has an hour-glass shape which facilitates the winding of wire around post 12, as will be described. Typically, tin-

lead plated copper alloy terminals are molded into the wall of the package 10 with the terminals extending through and below the bottom of the wall. The outer portion of the package 10 is formed to meet specified footing requirements. The inner post 12 serves as a terminal for internal wire termination use. The package material is made of type of thermal plastic which is in compliance with UL V-94 requirement for flammability.

Figure 2 shows a wound toroid transformer 20 with wire 22 wrapped around the transformer 20. The toroid core is typically made of ferrite material and the winding of wire 22 is done manually with fine insulated magnet wire.

Figure 3 shows a cut-away of the molded part with the toroid 20 mounted inside and showing the wire 22 as it is then attached to post 14. The wires 22 are pulled with minimum tension and wrapped around the terminal post 14 for two to two and a half turns. This operation is done when the case has been placed bottom side up.

Figure 4 shows a silicone compound 30 poured inside the cavity with wire terminations that have been soldered with high temperature solder (95 Ag/5Sn) 32 and the package has been properly cleaned. The case 10 is then filled with soft silicone material (preferably a soft epoxy type material) to protect the transformer and to meet environmental requirements.

Figures 5 and 6 show the relationships between the safe guard (stand off) 34 and package's foot seating plane and inner terminal posts 12a. Figure 5 shows the standoff 34, in which the parts typically are placed automatically by machine onto a PC board. They are pressed down, as it is desirable to have some limitation of how far they can be pressed. It is also desirable that the post 12 does not touch the PC board, and so the end standoffs 34 do not allow that to happen. In a preferred embodiment, post 12 is oriented substantially perpendicular to, but does not touch, PC board.

Figure 6 shows the distance in relationship between the end of the post 12 and where the PC board 36 is located and also where the standoff 34 ends. The PC board 36 would be at the base of the foot.

In Figure 6, the typical clearance of 0.015 inches from the safe guard 34 to the seating plane is to avoid interference to the coplanarity of the package. There is also a gap between the safe guard 34 and terminal post 12 to prevent the solder joints from touching the circuit board due to an over forced pick and place operation.

5        Inside the package 10, there may be two, three, or more individual toroidal transformers. Wires coming off of the transformers are connected to the outside world. For example, the pins may be mounted on a printed circuit board in an electronic device. The leaf frame pins are injection molded into the body and which allows for an exposed notched post upon which the wire is wound from the toroidal transformer. This allows for the wires to be separated from pin to pin, and for soldering to be much more efficient.

10        Figure 7 shows a closeup of the hour-glass shaped pin 12 and how pin 12 is molded inside the wall of the body and also the notch effect 40 of the pin 12. The post 14 is notched so that the wires are kept away from another, post to post, which is very desirable. The separation is desirable so as to avoid arcing.

15        Figure 8 shows the wire 22 wrapped around the pin or post 12.

20        Figures 9A-9D show end, top, side, and bottom views, respectively, of the electronic surface mount package 10. The embodiment shown in Figures 9A-9D provide an industrial standard surface mount footprint and package dimensions which are auto pick and placeable. In addition, special design consideration has been applied to thermal expansion of materials to ensure that the package will stand all normal re-flow processes with low cost, easy manufacturing, and high reliability.

25        In the industry, most manufacturers have used a two-piece construction, a base and a cover, and the case is backfilled with hard epoxy. In some processes, the coefficients of expansion of the epoxy that has been backfilled tends to cause the two pieces to separate. The base separates from the top, and as a result, can end up cracking. The present invention provides a one-piece open construction (an open bottom) only with the soft silicone filling to protect the

toroid. The case is open at the bottom, thus allowing the toroids to expand naturally without cracking the body of the part.

Figure 10 shows a bottom view of a 40 pin package 30 which includes pins 32 which includes a reinforcement beam 36 laterally disposed across the bottom of the case or package 30  
5 reinforcement beam 36 provides extra support for improving the mechanical strength of the package 30.

Figure 11 shows an enlarged sectional view of the package 30 of Figure 10 in which the reinforcement beam 36 is disposed laterally or sidewise across the bottom of the package or case 30. The 40 pin surface mount package shown in Figures 10 and 11 include the reinforcement  
10 beam 36 which provides extra support to the mechanical strength of the package 30. This provides for an improved mechanically stable package 30 which when undergoing an IR (infrared) re-flow process and also maintain the coplanarity of the leads or pins 32 shown in Figure 11.

Although Figure 11 shows one reinforcement beam 36 laterally disposed across the  
15 bottom of the case or package 30, it would be apparent to one of ordinary skill in the art that additional reinforcement beams can be located on the bottom of the case or package 30 as the situation warrants.

It should become apparent that various desirable features of the present invention have been shown and described. In the present invention, the pin termination is not flush mounted but  
20 rather extends from the bottom of the package. Further, the termination is wound and soldered to the extended pin-post package, as shown in Figures 1 and 3-8. The use of a soft silicone material (such as soft epoxy) to carry the toroid transformers within the case or package acts to encapsulate or support the toroid transformer within the case or package.

25 ELECTRONIC SURFACE MOUNT PACKAGE WITH EXTENDED SIDE  
RETAINING WALL EMBODIMENT

The features of the electronic surface mount package with extended side retaining wall embodiment will now be described in conjunction with Figures 12-16. The electronic surface mount package according to the present invention includes a one piece construction package having end walls, a side wall and an open bottom; a plurality of toroid transformers carried within the package by a soft silicone material wherein the toroid transformers each have wires wrapped thereon; a plurality of terminal pins molded within and extending from the bottom of the package wherein each of the pins extend through a bottom portion of the side wall and have a notched post upon which the wires from said transformers are wrapped and soldered thereon, respectively; and wherein the end walls have a first height H1 to form a standoff or safe guard between the foot seating plane of the package and the terminal pins; and wherein the outer portion of the side wall extends between the end walls such that the side wall has a second height H2 which is less than said first height H1.

Figures 12 shows a three dimensional view of an electronic surface mount package 50 with a side wall 56 having an extended side retaining wall portion 58 according to the present invention. The view shown in Figure 12 is similar to that view shown in Figure 1, with the addition of the extended side retaining wall portion 58. The end wall 52 forms a safeguard 54 shown in Figure 12, and which is similar to safeguard 34 shown in Figures 5 and 6. The end wall 52 has a height H1. The solder post 60 and leads 62 shown in Figure 12 are also similar to posts 12 and leads 14 shown in Figure 1. As can be seen in Figure 12, the extended side retaining wall portion 58 extends from the remaining portion of side wall 56 so as to form a projection or ledge. Preferably, the height H2 of the side wall 56 including the extended side retaining wall portion 58 is less than the height H1 of the end wall ( $H2 < H1$ ).

As will be understood, the extended side retaining wall outer portion 58 provides for improved containment of the soft silicone material within the package. The extended side retaining wall portion 58 also provides for improved coverage of the wire wrapped solder posts 60. In addition, since the height H2 of the extended side retaining wall portion 58 is less than the

height H1 of the safe guard 54, the mounting of the package 50 onto a printed circuit board with the extended side retaining wall portion 58 allows for cleaning of the PCB with wash liquids which can flow freely under the package 50 under the portion of the extended side wall portion 58 which is less in height than the height of the safeguard ( $H2 < H1$ ).

5 Figure 13 shows a bottom view of the package 50 of Figure 12, in which the side retaining wall portion 58 is located between the respective safeguards (end walls) 54. The bottom of each terminal pin 60 can also be seen, as well as the leads 62. For clarity purposes, the bottom view of the package shown in Figure 13 does not include the toroid transformers and silicone material shown in Figures 5,6 and 9-D. However, a complete electronic surface mount  
10 package 50 according to the present invention would include the toroid transformers and a soft silicone material.

Figure 14 shows a more detailed three dimensional view of the electronic surface mount package 50 with extended side retaining wall portion 58 according to the present invention. The package 50 shown in Figure 14 includes the side wall 56 with the extended side retaining wall portion 58, terminal posts 60, leads 62, end wall 52 which forms safeguard 54, and  
15 soft silicone material 66. It can be seen in Figure 14 that the extended side retaining wall portion 66 provides additional coverage of the soft silicone material 66 as well as more coverage of the posts 60. Also, because the height H2 of the side wall 56 is less than the height H1 of the end wall (safeguard) 52, the mounting of the package 50 onto a printed circuit board with the  
20 extended side retaining wall portion 58 allows for cleaning of the PCB with wash liquids which can flow freely under the package 50 under the portion of the extended side wall portion 58 which is less in height than the height of the safeguard ( $H2 < H1$ ).

Figure 15 shoes a cross sectional end view of the electronic surface mount package 50 with extended side retaining wall portion 58 according to the present invention. The package 50  
25 shown in Figure 15 includes the toroid transformer 70 carried by the soft silicone material 66, safeguard 54, lead 62, side wall 56 including the extended side retaining wall portion 58 and the

terminal post 60 with wire 74 wrapped thereon and soldered by solder joint 72. It can be seen in Figure 15 that the side wall 56 including the extended side retaining wall portion 58 has a height H2 which is less than the height H1 of the safe guard (end wall) 54. As previously described, the end walls 52 have a first height H1 to form a standoff or safe guard 54 between the foot seating plane of the package 50 and the terminal posts 60, and the outer portion 58 of the side wall 56 extends between the end walls 52 such that the side wall 56 has a second height H2 which is less than said first height H1. The mounting of the package 50 onto a printed circuit board (PCB) with the extended side retaining wall portion 58 according to the present invention allows for cleaning of the PCB with wash liquids which can flow freely under the package 50 under the portion of the extended side wall 58, since the height of the extended side retaining wall (H2) is less than the height of the safeguard H1 ( $H2 < H1$ ). As also previously described, the extended side retaining wall 58 provides for improved containment or coverage of the soft silicone material 66 within the package 50. The extended side retaining wall portion 58 also provides for improved coverage of the wire wrapped solder posts 60.

Figure 16 shows a close up view of one terminal post 60 contained within the electronic surface mount package 50 with extended side retaining wall portion 58 according to the present invention. Figure 16 shows the terminal post 60 with wire 74 wrapped thereon. Figure 16 clearly shows the improved extended coverage of the soldered terminal posts 60 by the extended side retaining wall portion 58 according to the present invention.

The present invention is directed toward applications for packages mounted on a printed circuit board in an electronic device, which requires very low current and voltages, and is for DC voltages only. The present invention provides for a low power application in which the package includes one or more toroidal transformers which are carried or supported by a soft silicone material within an open construction package and which utilizes a portion of the case as a standoff to ensure that the pin-posts do not touch a PCB when mounted by a user.

It is widely known that when the toroidal magnetics are mounted in hard plastic



packages, the infra-red soldering processes cause the magnetic components (ferrite) to expand significantly. When using a hard epoxy type material, it has been found that the magnetic component expansion can often cause cracking of the package or case, which is highly undesirable. The present invention solves this problem by providing an open design within  
5 which is placed a soft silicone material which allows for expansion during the soldering process, rather than contain the components within a closed case or package. Hence, with the open construction, the present invention has no bottom at all. In addition, the magnetic components are not mounted on anything but rather are encapsulated or supported ("carried by a soft silicone material") such that when the wires are wound around and soldered to the pin-posts, the cracking and expansion problems described above are avoided.

As has been described, the electronic surface mount package according to the present invention includes a one piece construction package having end walls, a side wall and an open bottom; a plurality of toroid transformers carried within the package by a soft silicone material wherein the toroid transformers each have wires wrapped thereon; a plurality of terminal pins  
15 molded within and extending from the bottom of the package wherein each of the pins extend through a bottom portion of the side wall and have a notched post upon which the wires from said transformers are wrapped and soldered thereon, respectively; and wherein the end walls have a first height H1 to form a standoff or safe guard between the foot seating plane of the package and the terminal pins; and wherein the outer portion of the side wall extends between the end  
20 walls such that the side wall has a second height H2 which is less than said first height H1.

The extended side retaining wall provides for improved containment of the soft silicone material within the package. The extended side retaining wall also provides for improved coverage of the wire wrapped solder posts. In addition, since the height H2 of the extended side retaining wall is less than the height H1 of the safe guard, the mounting of the package onto a  
25 printed circuit board with the extended side retaining wall allows for cleaning of the PCB with wash liquids which can flow freely under the package under the portion of the extended side wall

which is less in height than the height of the safeguard ( $H2 < H1$ ).

The foregoing descriptions of specific embodiments of the present invention have been presented for purposes of illustration and description. They are not intended to be exhaustive or to limit the invention to the precise forms disclosed, and it should be understood that many  
5 modifications and variations are possible in light of the above teaching. The embodiments were chosen and described in order to best explain the principles of the invention and its practical application, to thereby enable others skilled in the art to best utilize the invention and various embodiments with various modifications as are suited to the particular use contemplated. It is intended that the scope of the invention be defined by the Claims appended hereto and their  
10 equivalents.

WHAT IS CLAIMED IS:

1. An electronic surface mount package comprising:

5 a one piece construction package having end walls, a side wall and an open bottom,  
a plurality of toroid transformers carried within said package by a soft silicone material,  
said toroid transformers each having wires wrapped thereon;

10 a plurality of terminal pins molded within and extending from the bottom of said  
package, each of said pins extending through a bottom portion of said side wall and having a  
notched post upon which said wires from said transformers are wrapped and soldered thereon,  
respectively;

said end walls having a first height H1 to form a standoff or safe guard between the foot  
seating plane of said package and said terminal pins;

15 the outer portion of said side wall extending between said end walls and having a second  
height H2 which is less than said first height H1.

2. An electronic surface mount package  
comprising:

20 a construction package having end walls, a side wall and an open bottom,  
a plurality of toroid transformers carried within said package by a soft silicone material,  
said toroid transformers each having wires wrapped thereon,

25 a plurality of terminal pins molded within and extending from the bottom of said  
package, each of said pins extending through a bottom portion of said wall and having a notched  
post upon which said wires from said transformers are wrapped and soldered thereon,  
respectively.

said end walls having a first height H1 to form a standoff or safe guard between the foot

seating plane of said package and said terminal pins;

the outer portion of said side wall extending between said end walls and having a second height H2 which is less than said first height H1.

5

3. A package as in Claim 2 wherein said construction package is one piece.

4. The package of Claim 3 wherein said posts are separated from one another so as to avoid arcing.

5. An electronic surface mount package for mounting on a printed circuit board in an electronic device, said electronic surface mount package comprising:

a one piece construction package having end walls, a side wall and an open bottom, a plurality of toroid transformers carried within said package by a soft silicone material, said toroid transformers each having wires wrapped thereon,

a plurality of terminal pins molded within and extending from the bottom of said package, each of said pins extending through a bottom portion of said side wall and having a notched post upon which said wires from said transformers are wrapped and soldered thereon, respectively,

said end walls having a first height H1 to form a standoff or safe guard between the foot seating plane of said package and said terminal pins;

the outer portion of said side wall extending between said end walls and having a second height H2 which is less than said first height H1.

6. The package as in Claim 5 further including a standoff for maintaining a distance between the bottom of said pins and said printed circuit board.

5  
7. An electronic surface mount package comprising:  
a construction package having end walls, a side wall and an open bottom,  
at least one toroid transformer carried within said package by a soft silicone material, said  
toroid transformer having a wire wrapped thereon,  
10 at least one terminal pin molded within and extending from the bottom of said package,  
said pin extending through a bottom portion of said side wall and having a notched post upon  
which said wire from said transformer is wrapped and soldered thereon,  
said end walls having a first height H1 to form a standoff or safe guard between the foot  
seating plane of said package and said terminal pins;  
15 the outer portion of said side wall extending between said end walls and having a second  
height H2 which is less than said first height H1.

20 8. An electronic surface mount package for mounting on a printed circuit board in an  
electronic device, said package comprising:  
a one piece open construction package having end walls, side walls and an open bottom,  
a plurality of toroid transformers carried within said package, said toroid transformers  
each having a side wall and wires wound thereon,  
25 a plurality of terminal pins molded within and extending through a bottom of said side  
wall, each of said pins having a hour-glass shaped notched post upon which said wires from said  
transformers are wrapped thereon, respectively,

said end walls having a first height H1 to form a standoff or safe guard between the foot seating plane of said package and said terminal pins;

the outer portion of said side wall extending between said end walls and having a second height H2 which is less than said first height H1.

ABSTRACT OF THE DISCLOSURE

5 The electronic surface mount package according to the present invention includes a one piece construction package having end walls, a side wall and an open bottom; a plurality of toroid transformers carried within the package by a soft silicone material wherein the toroid transformers each have wires wrapped thereon; a plurality of terminal pins molded within and extending from the bottom of the package wherein each of the pins extend through a bottom portion of the side wall and have a notched post upon which the wires from said transformers are wrapped and soldered thereon, respectively; and wherein the end walls have a first height H1 to form a standoff or safe guard between the foot seating plane of the package and the terminal pins; and wherein the outer portion of the side wall extends between the end walls such that the side wall has a second height H2 which is less than said first height H1. The extended side retaining wall provides for improved containment of the soft silicone material within the package. The extended side retaining wall also provides for improved coverage of the wire wrapped solder posts. In addition, since the height H2 of the extended side retaining wall is less than the height H1 of the safe guard, the mounting of the package onto a printed circuit board with the extended side retaining wall allows for cleaning of the PCB with wash liquids which can flow freely under the package under the portion of the extended side wall which is less in height than the height of the safeguard ( $H1 < H2$ ).

10  
15  
20

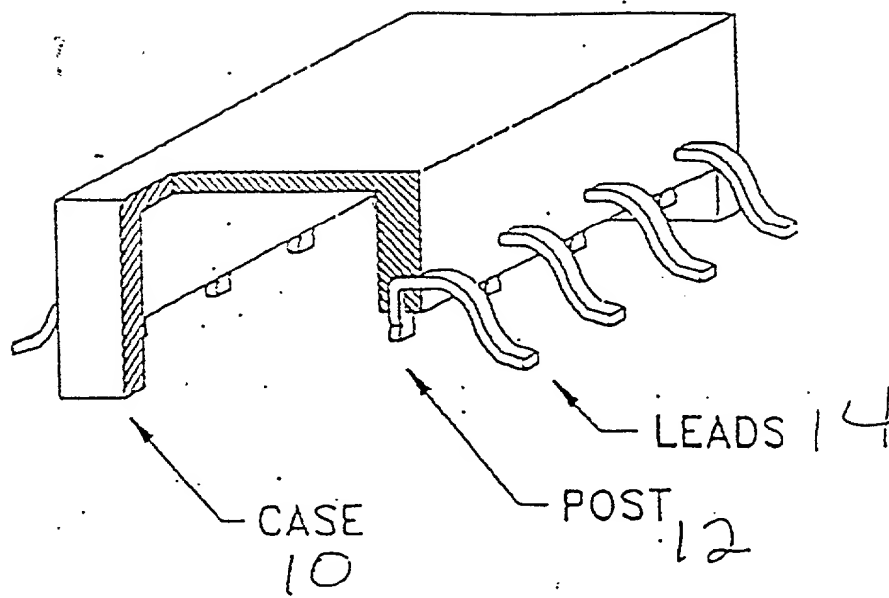


FIGURE 1

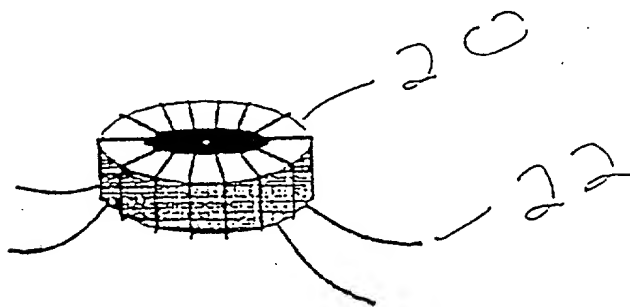


FIGURE 2

0897480-12497



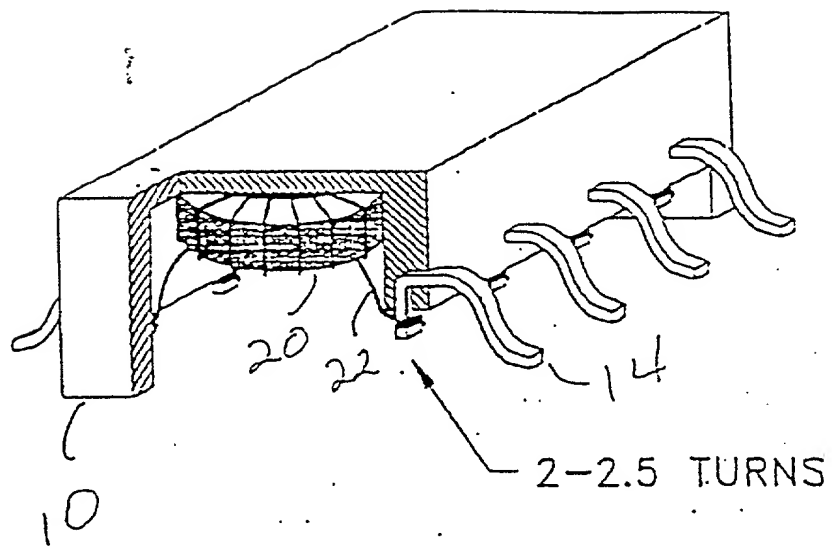


FIGURE 3

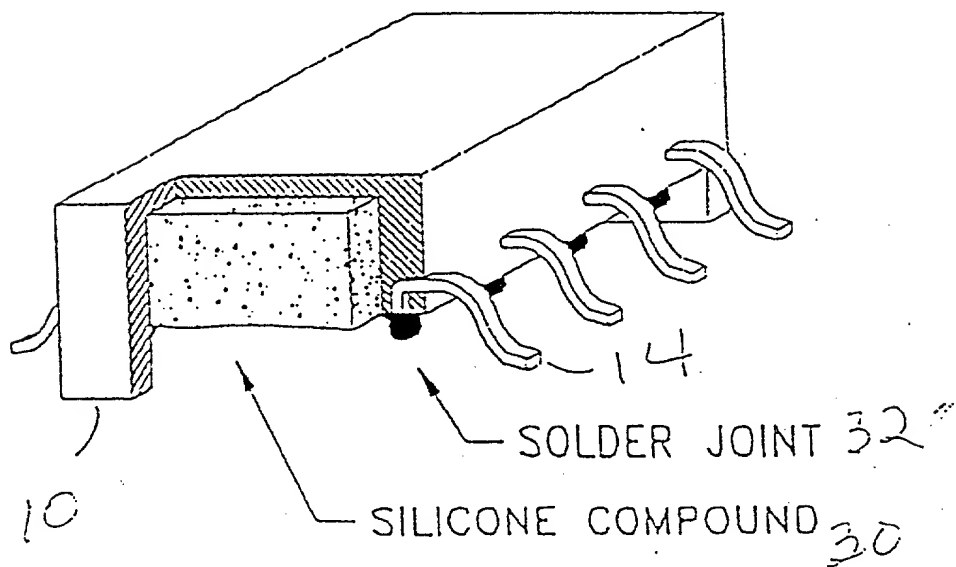


FIGURE 4

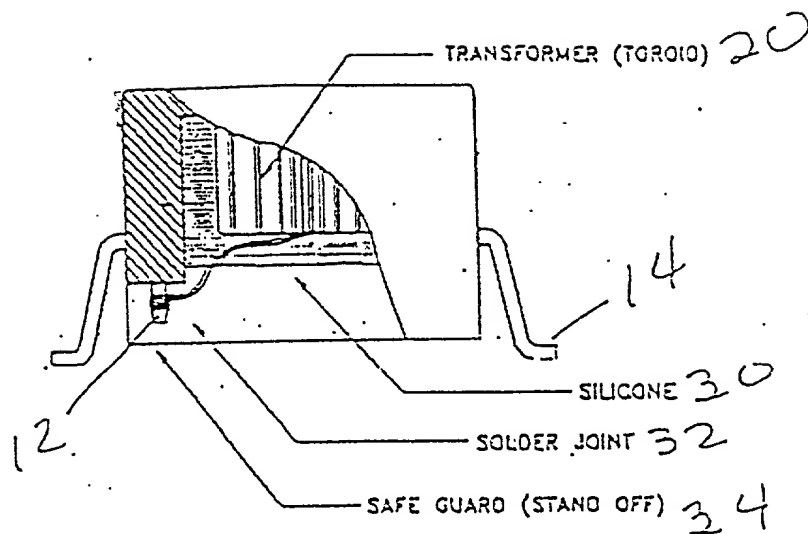


FIGURE 5

CLOSE UP

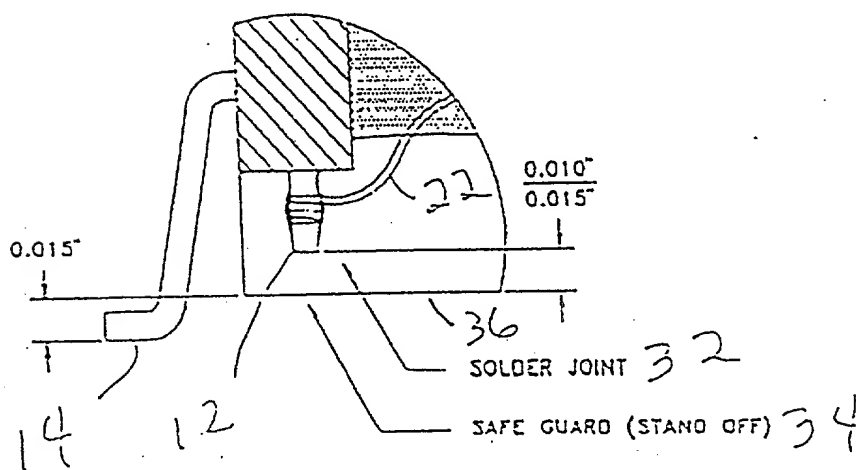


FIGURE 6

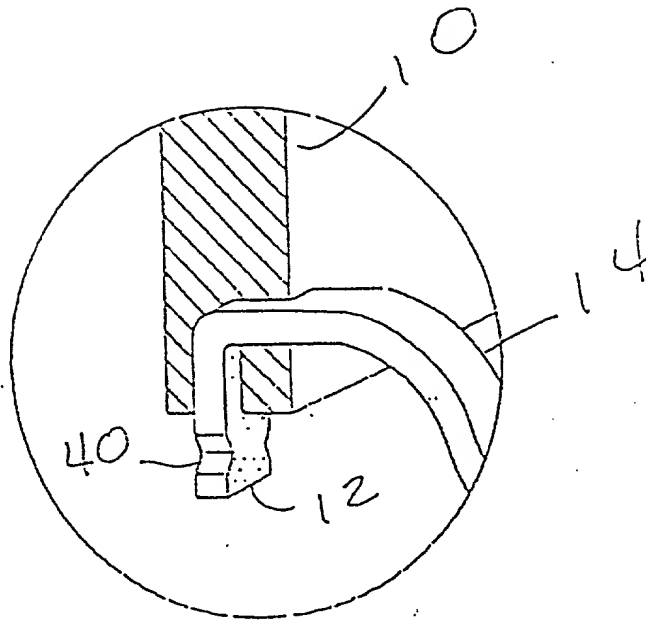


FIGURE 7

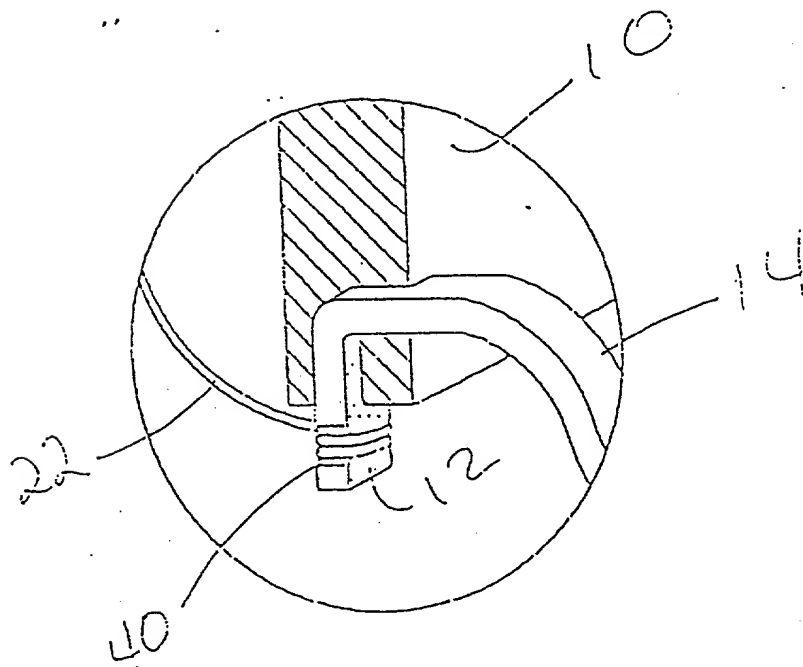
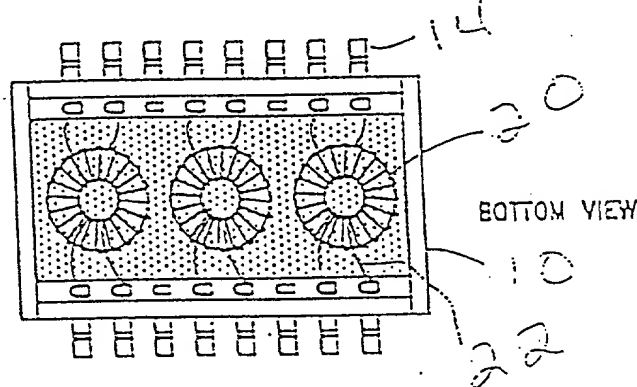
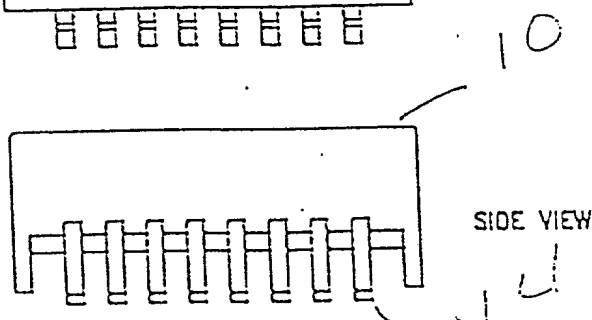
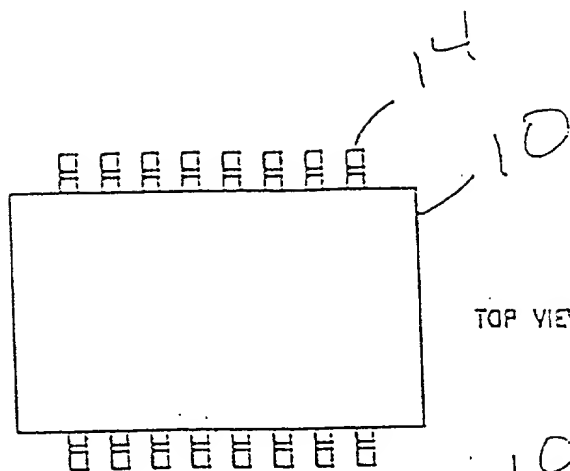
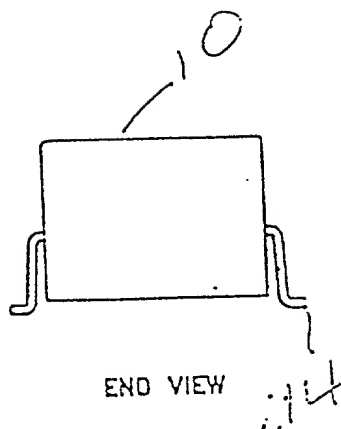


FIGURE 8

64477430-1 11197

9-A



9-B

9-C

9-D

FIGURE 9

FIGURE 10

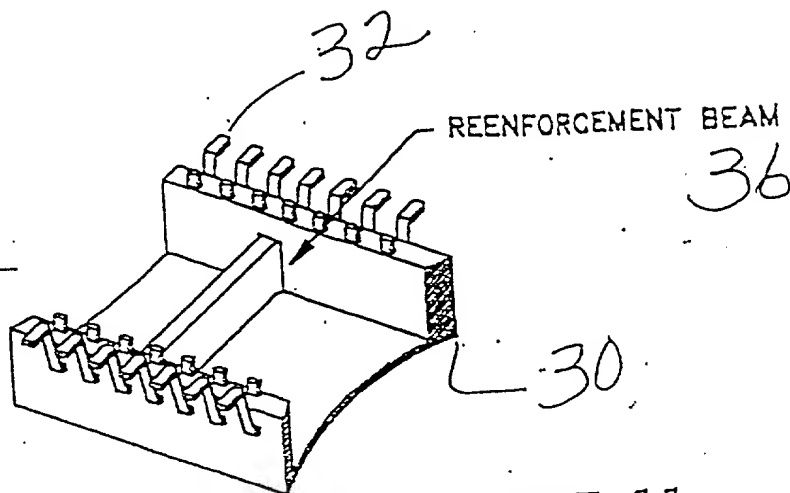
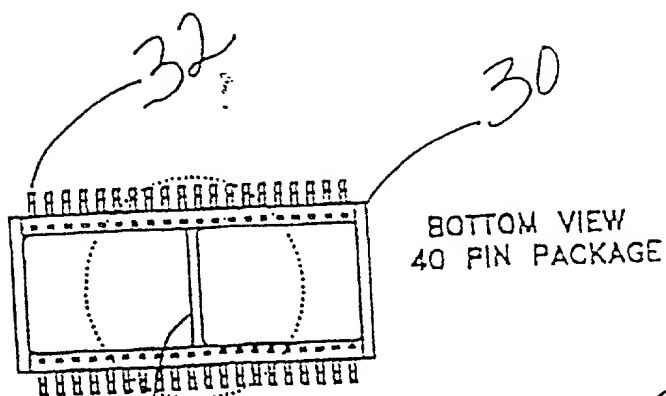


FIGURE 11

ENLARGED  
SECTIONAL VIEW

HALO 40PIN SURFACE MOUNT PACKAGE INCORPORATES A REENFORCEMENT BEAN WHICH IN TURN PROVIDES EXTRA SUPPORT TO THE MECHANICAL STRENGTH OF THE CASE. IT IS ESSENTIAL TO HAVE A MECHANICALLY STABLE PACKAGE WHEN GOING THROUGH IR RE-FLOW PROCESS AND MAINTAIN THE LEADS CO-PLANARITY.

50

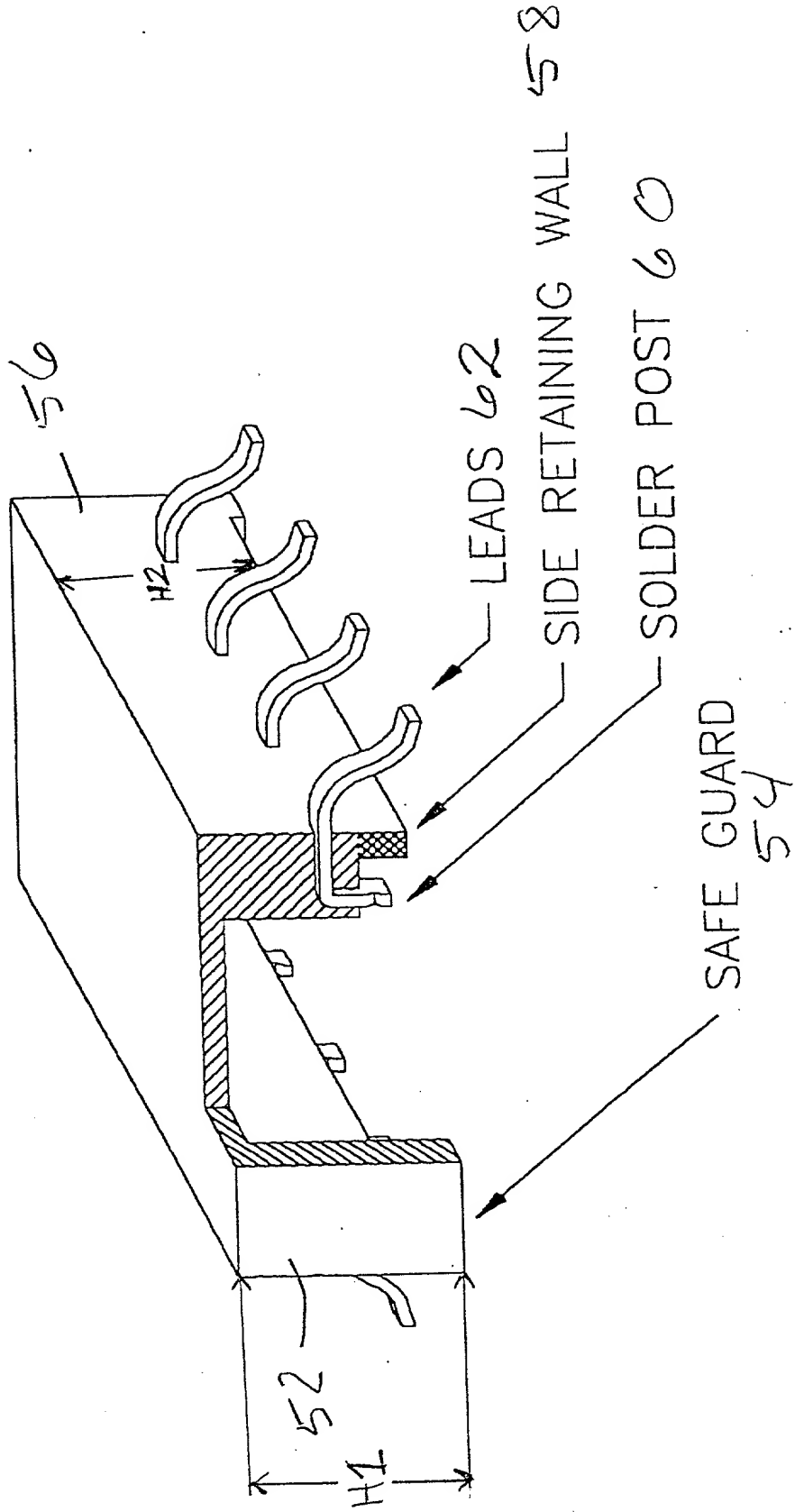


FIGURE 12

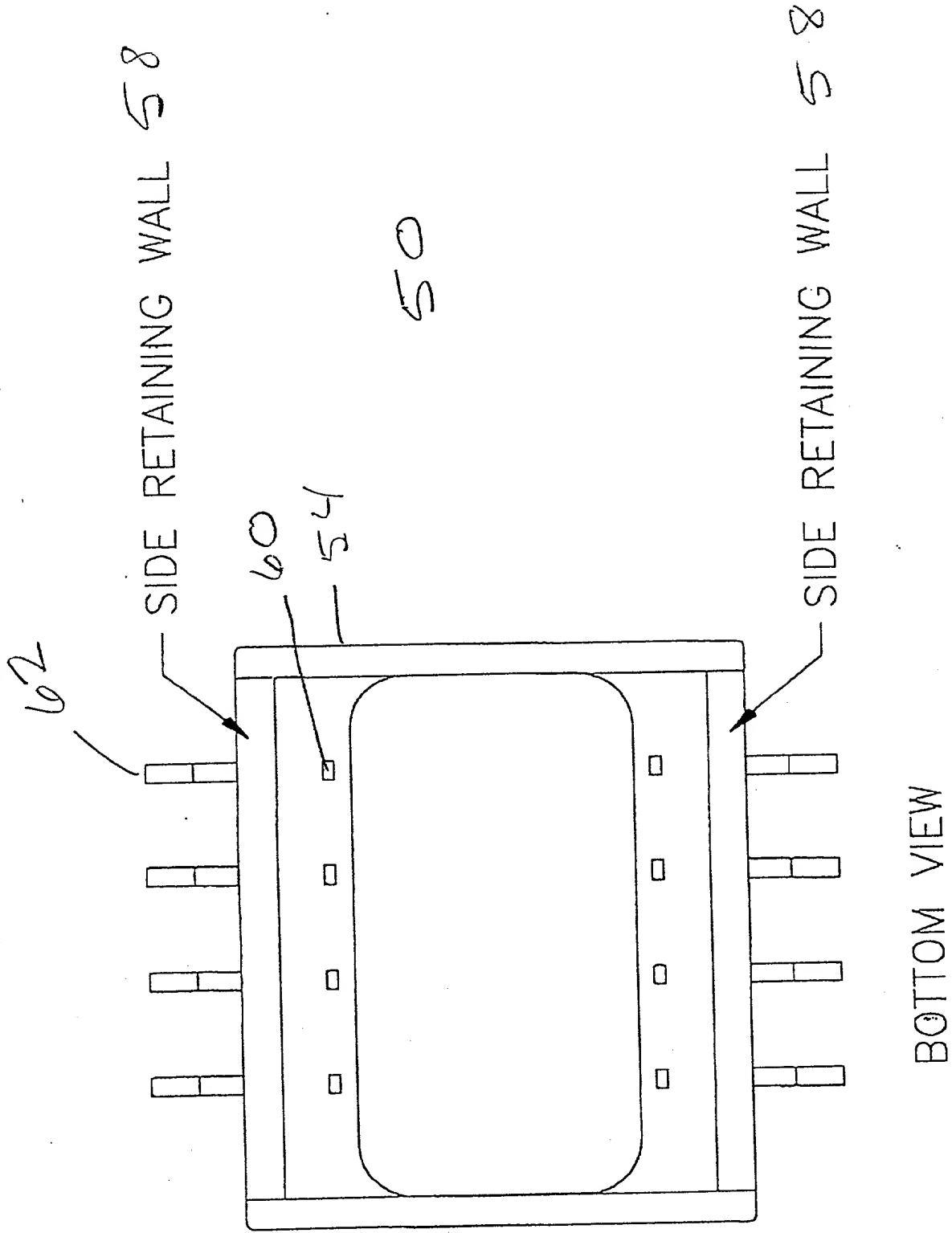


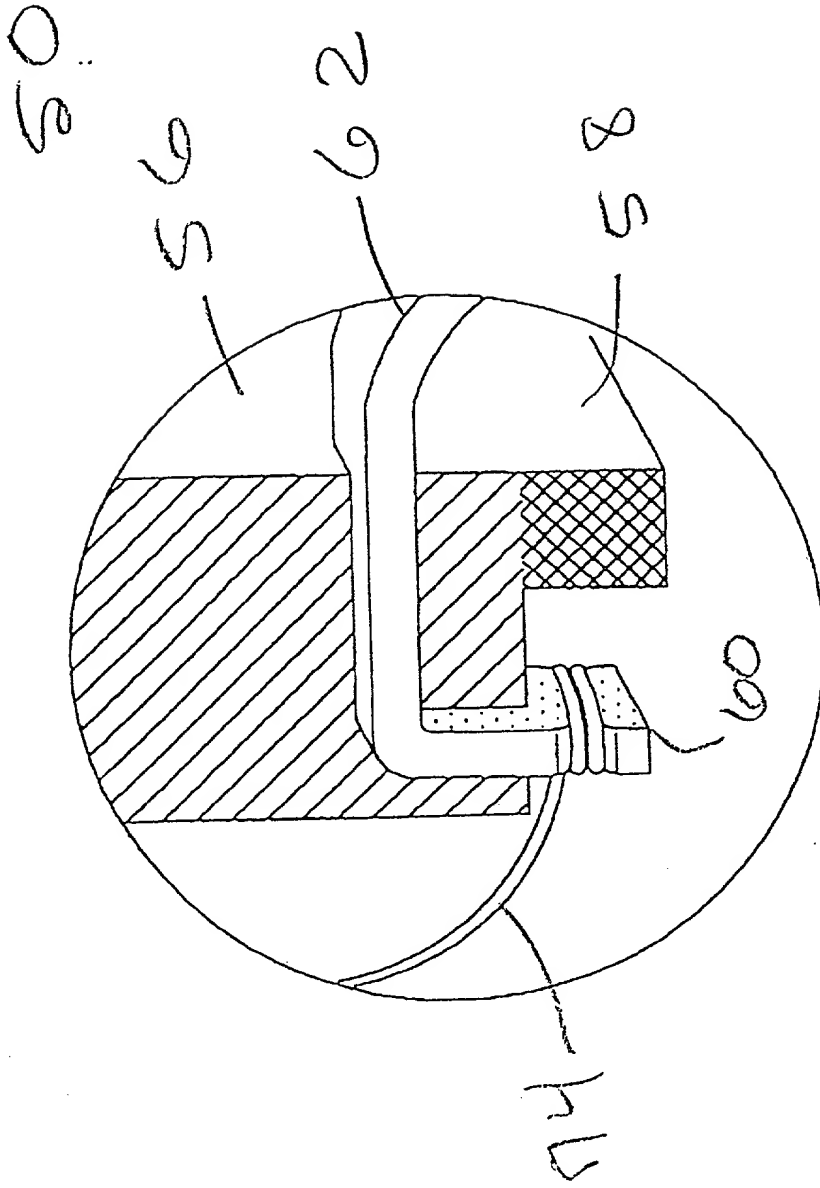
FIGURE 13

Oh









CLOSE UP

FIGURE 16